Egis Technology Inc.

2025Q3 Investor Conference

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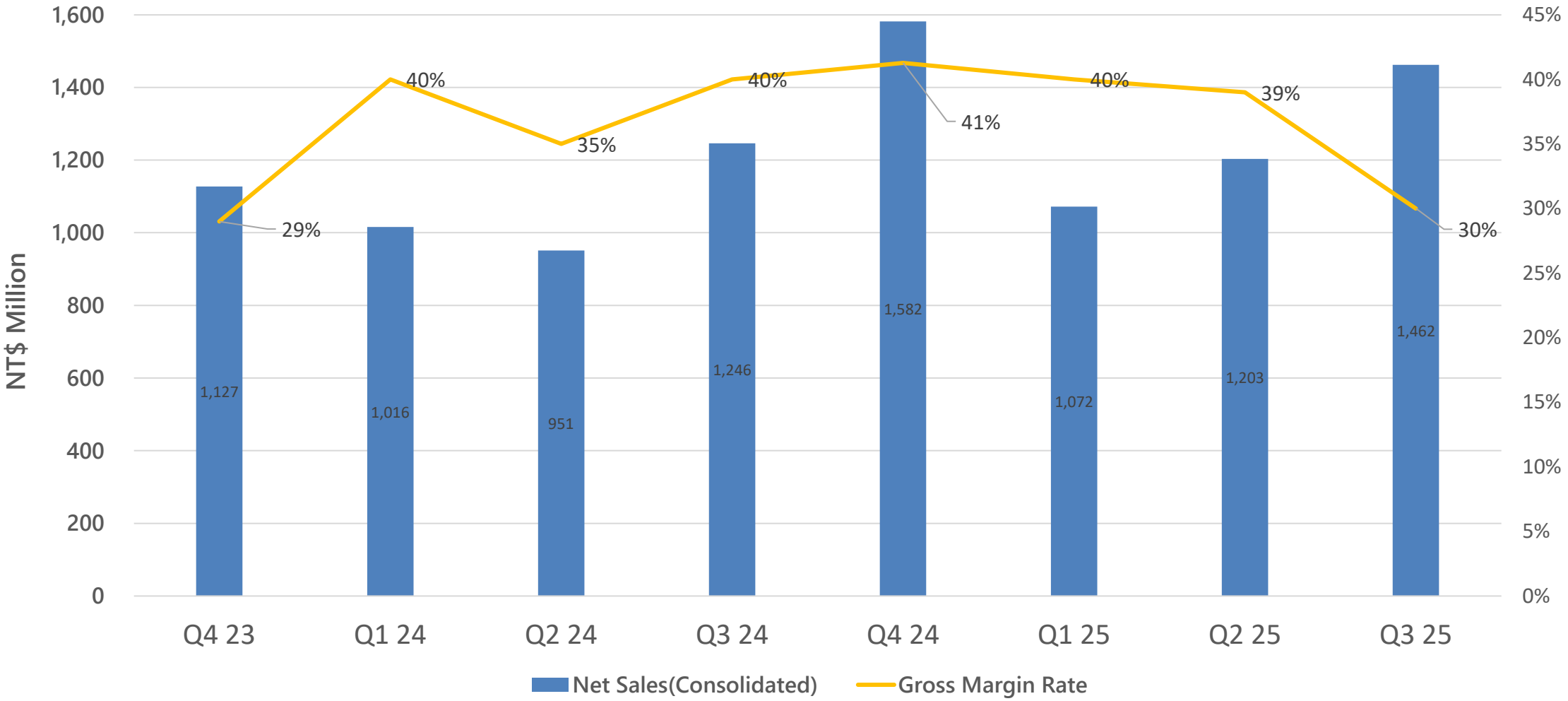
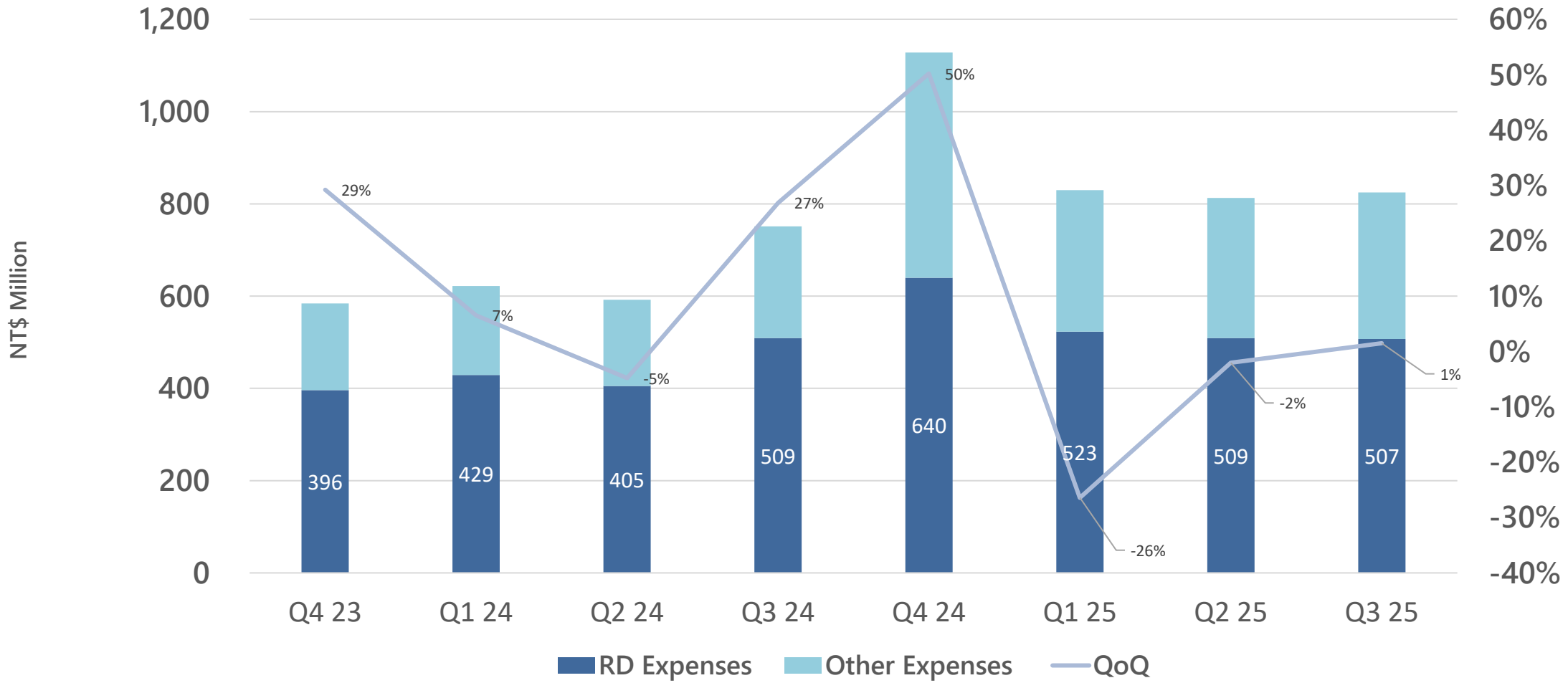
2025.12.22

Revenue and GM trend



Operating Expenses



Income Statement Q3 2025 vs. Q3 2024

Unit: NT$ Thousands	Q3 2025	Q3 2024	Growth Rate
Net Sales	1,462,317	1,246,186	17%
COGS	1,018,769	745,752	
Gross Profit	443,548	500,434	-11%
Gross Margin	30.3%	40.2%	
Operating Expense	825,116	751,163	
Operating Income	(381,568)	(250,729)	-52%
Operating Margin	-26%	-38%	
Non-operating Income and Expense	23,228	(94,457)	
Income before Tax	(358,340)	(345,186)	
Income Tax Expense (Income)	227,772	(15,355)	
Income after Tax	(586,112)	(329,831)	
Minority Interest	(142,459)	(105,654)	
Parent Net Income (Loss)	(443,653)	(224,177)	-98%
Net Margin	-30.3%	-18.0%	
EPS (NT$)	(4.86)	(2.68)	

Income Statement Q3 2025 vs. Q2 2025

Unit: NT$ Thousands	Q3 2025	Q2 2025	Growth Rate
Net Sales	1,462,317	1,203,233	22%
COGS	1,018,769	733,260	
Gross Profit	443,548	469,973	-6%
Gross Margin	30.3%	39.6%	
Operating Expense	825,116	813,263	
Operating Income	(381,568)	(343,290)	-11%
Operating Margin	-26%	-29%	
Non-operating Income and Expense	23,228	(218,655)	
Income before Tax	(358,340)	(561,945)	
Income Tax Expense (Income)	227,772	(52,840)	
Income after Tax	(586,112)	(509,105)	
Minority Interest	(142,459)	(79,759)	
Parent Net Income (Loss)	(443,653)	(355,606)	-25%
Net Margin	-30.3%	-29.6%	
EPS (NT$)	(4.86)	(3.90)	

Balance Sheet (1)

Unit: NT$ Thousands	Q3 2025	Q3 2024
Cash and cash equivalents	3,162,666	2,041,545
Financials assets at fair value through P&L	192,208	298,695
Notes and accounts receivable, net	554,837	618,371
Inventories	437,416	588,210
Prepaid Expenses	1,447,474	546,139
other current assets	296,299	165,227
Total current assets	6,512,476	4,910,993
Non-current assets		
Financials assets at fair value through P&L	498,857	638,041
Financials assets at fair value through OCI	1,693,114	2,191,821
Investments accounted for using equity method	1,067,422	1,308,202
other non-current assets	143,572	206,068
Total non-current assets	13,297,276	14,795,533
Total Assets	**19,809,752**	**19,706,526**

Balance Sheet (2)

Unit: NT$ Thousands	Q3 2025	Q3 2024
Current liabilities		
Short-term borrowings	1,139,125	1,119,750
Notes and accounts payable	219,796	259,580
Long-term liabilities, current portion	309,829	920,000
other current liabilities	3,740,490	2,329,975
Total current liabilities	5,409,240	4,629,305
Non-Current liabilities		
Long-term debt	228,249	2,684,000
other non-current liabilities	1,016,464	1,710,674
Total non-ccurrent liabilities	1,244,713	4,394,674
Total Liabilities	**6,653,953**	**9,023,979**
Total Equity	**13,155,799**	**10,682,547**

Building Chiplet Marketplace

2025Q3 Investor Conference

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為何需要 Chiplet？

- 摩爾定律
- AI/HPC需求

實踐中的挑戰：Chiplet 設計的關鍵考量

1. **先進封裝技術**： 將多個 Chiplet 精密封裝於同一系統中，需仰賴複雜且昂貴的先進封裝技術，如 2.5D（使用矽中介層）或 3D 封裝；相關的**成本、產能與良率**仍需持續優化。

2. **互連效能**： 雖然 UCIe 已有效降低 D2D 的延遲與功耗，但晶片間通訊仍難以完全媲美單體晶片內部連接，對高效能運算架構帶來設計挑戰。 。

3. **散熱管理**： 將多個高效能 Chiplet 緊密堆疊或排列在一起，將造成高度熱密度，散熱設計成為封裝與系統層面的關鍵課題。

4. **測試與驗證**： 在封裝之前，必須確保每一個 Chiplet 都是**功能完好（Known Good Die, KGD）**；開發高效且可靠的 KGD 測試方法，以及在封裝後對整個 **SiP 進行系統級的測試與驗證**，都增加了額外的複雜性。

5. **標準化與生態系成熟度**： 儘管 UCIe 提供基礎標準，完整的 Chiplet 生態系仍需時間發展，**包含 IP 多樣性、設計工具支援與供應鏈整合**。

UCIe 技術解密：通用小晶片互連快車道

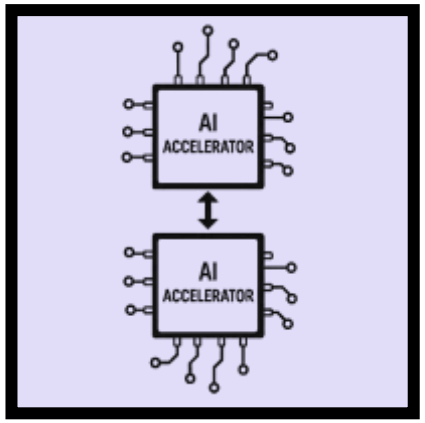
- UCIe 標準定義了一套 完整、分層的 **D2D 互連協定堆疊**，實現**高頻寬、低延遲、低功耗**的晶片間通訊。

- UCIe 的技術架構可分為 三個關鍵層級：
  1. **實體層（Physical Layer, PHY）**負責**原始電子訊號的傳輸**提供多種 PHY 選項，可支援不同封裝技術與應用情境：
     標準封裝（如有機基板）
     先進封裝（2.5D / 3D，例如**TSMC CoWoS**、Intel **EMIB / Foveros**）讓 UCIe 能在效能與成本之間保持高度彈性。

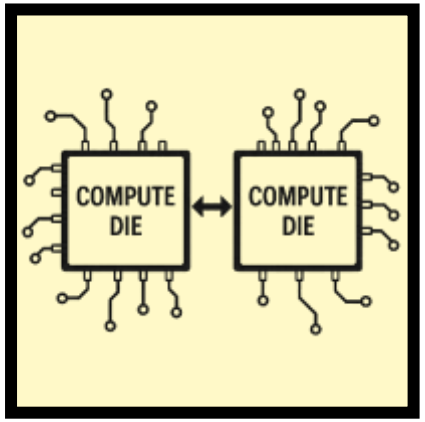
  2. **裸晶到裸晶適配層（Die-to-Die Adapter）**負責**鏈路管理、參數協商與錯誤偵測**確保 D2D 連線的**可靠性與穩定性**。

  3. **協定層（Protocol Layer）**定義 Chiplet 之間**資料傳輸的運作規則**，原生支援業界主流協定：**PCI Express（PCIe）**：I/O 連接；**Compute Express Link（CXL）**：高效記憶體共享與一致性（Coherency）。
     適用於 **CPU、GPU 與 AI 加速器** 等高資料量應用，可與 既有系統架構無縫整合。

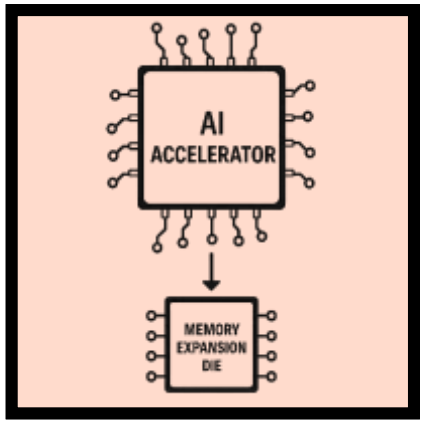
UCIe Use Cases…We will see more in the future



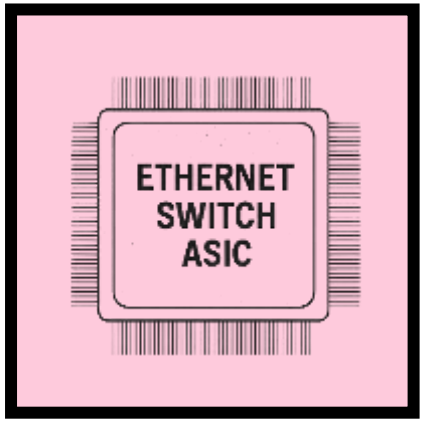
AI Accelerators



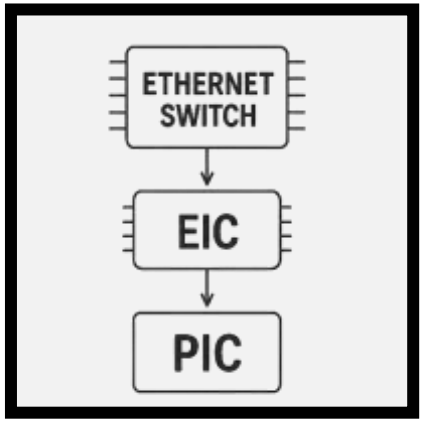
Compute Dies



IO/Mem. Expansion Dies



Network Switch



Optical I/O Chiplets

Evolution of Chiplet